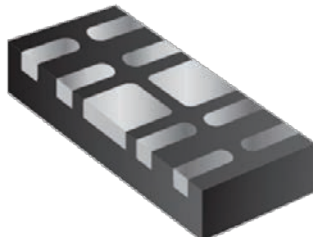


MATERIAL DECLARATION SHEET



Material Number	ESD Suppressing Device CDDFN10-3324P			
Product Line	Semiconductor Products			
Compliance Date	2014/9/5			
RoHS Compliant	Yes	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.3500	Silicon	7440-21-3	100.00%	7.991%	7.991%
2	Lead frame	Copper Alloy	1.8900	Copper	7440-50-8	95.44%	41.185%	43.151%
				Iron	7439-89-6	2.40%	1.037%	
				Phosphorus	7723-14-0	0.10%	0.043%	
				Zinc	7440-66-6	0.15%	0.064%	
				Lead	7439-92-1	0.01%	0.002%	
				Silver	7440-22-4	1.90%	0.820%	
3	Epoxy	Polymer	0.1100	Epoxy Resin A	Trade Secret	15.00%	0.377%	2.512%
				Epoxy Resin B	Trade Secret	10.00%	0.251%	
				Phenol Resin	Trade Secret	15.00%	0.377%	
				SiO2 Filler	7631-86-9	50.00%	1.256%	
				Acrylic Copolymer	Trade Secret	10.00%	0.251%	
4	Wire	Noble metal	0.0700	Gold	7440-57-5	100.00%	1.598%	1.598%

MATERIAL DECLARATION SHEET



5	Mold Compound	Polymer	1.8400	Epoxy Resin	Trade Secret	5.00%	2.100%	42.008%
				Phenol Resin	Trade Secret	5.00%	2.100%	
				Silica (Amorphous) A	60676-86-0	74.00%	31.087%	
				Silica (Amorphous) B	7631-86-9	15.00%	6.301%	
				Carbon Black	1333-86-4	1.00%	0.420%	
6	Plating	Plating	0.1200	Tin	7440-31-5	100.00%	2.740%	2.740%
Total weight			4.3800mg					

This Document was updated on: 2014/09/03

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.